

## Lokotech AS: First silicon wafers out of fab

**Oslo, 26th of September 2026 – Lokotech AS ("Lokotech" or "the Company") can confirm that the first silicon wafers for the Company's Scrypt ASIC and Egde AI Inferencing chip has now finished processing at the foundry and are now «out of fab».**

This is an important milestone in Lokotech's ASIC development program. The first wafers have left fabrication at and will now will go through steps for getting the sliced die packaged followed by bring-up, tests and verification by production partners abroad as well as from the companys premises here in Norway. The Company expects to share more on test results and next steps when available.

"Getting first silicon out of fab is a major step for Lokotech and confirms the progress our team and suppliers have made. We now look forward to step-wise validating the chip's functions in physical silicon as well as performance." says Ola Stene-Johansen CEO of Lokotech Group AS.

For further information, please contact the company at [post@lokotech.no](mailto:post@lokotech.no)

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